# 12-31-1998

### Docket No. JC



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U.S. Department of Commerce Patent and Tradentark Office



PATENTS ONLY	12/17/92
To the Honorable Assistant Commissioner f original documents o	
1. Name of conveying party(ies):	2. Name/address of receiving Party(ies):
Li-Wu Tsao Cheng-Chieh Huang Tse-Wei Liu	United Silicon Incorporated
3. Nature of conveyance:   ☐ Merger ☐ Security Agreement ☐ Other ☐ Change of Name ☐ Reassignment	No. 3, Li-Hsin II Rd., Science-Based Industrial Park, Hsinchu, Taiwan, R.O.C.
4. Date(s) of execution: November 30, 1998;	Add'l names of receiving parties  Attached? Yes No
5. Application number(s) or patent number(s)	:
If this documents is being filed to execution date of the application is I	
A. Patent Application No. (s)	B. Patent No. (s)
09215586	
Additional numbers attached  Name and address of party to whom	<ul><li>? ☐ Yes ☒ No</li><li>7. Total No. of applications and patents</li></ul>
correspondence concerning document	involved:
should be mailed:	ONE(1)
J.C. Patents, Inc.	8. Total fee (37 CFR §3.41): \$40.00
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Jiawei Huang Name of Person Signing Signatu	Hang 12/12/18  Te Date
Registration No. 43, 330	

12/29/1998 DNGUYEN 00000084 09215586

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**PATENT REEL: 9664 FRAME: 0912** 

### **ASSIGNMENT**

WHEREAS.

1. Li-Wu Tsao

2. Cheng-Chieh Huang

3. Tse-Wei Liu

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: METHOD FOR CLEANING A SEMICONDUCTOR WAFER

[ ] Filed Serial No.

[x] Executed concurrently with the execution of this instrument

WHEREAS, United Silicon Incorporated of No. 3, Li-Hsin II Rd., Science-Based Industrial Park, Hsinchu, Taiwan, R.O.C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

-1-

## **ASSIGNMENT CONTINUED**

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Li-Wu Isao

November 30, 1998

Signature:

Sole or First Joint Inventor: Li-Wu Tsao

Signature: Thich Huring

November 30, 1998

Signature.

Second Joint Inventor (if any): Cheng-Chieh Huang

Tse-Wei Liu

November 30, 1998

Signature:

Third Joint Inventor (if any): Tse-Wei Liu

**RECORDED: 12/17/1998**